

Low-Profile LGA1366 Microprocessor Socket

Neoconix P/N: BDA1366MSF6AU00 > > >

Product Overview

OVERVIEW:

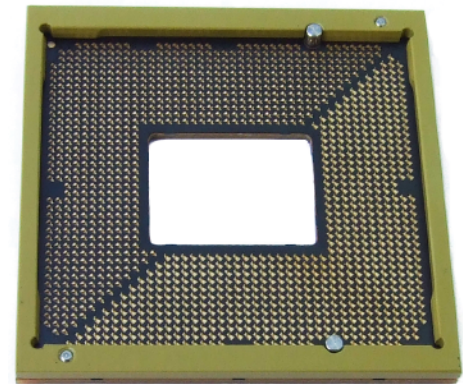
The Neoconix Low-Profile 1366-Position LGA Socket offers z-axis space savings for microprocessor socketing in space constrained and ruggedized applications. The reduced profile enables extra allowance for heatsink design and increased airflow. The product incorporates Neoconix's photolithography-based PCBeam™ Technology and offers outstanding true position in an FR-4 based connector substrate that is CTE-matched with the microprocessor and mainboard.

FEATURES:

- Low Profile: 1.7mm mated height after reflow
- Shorter electrical path than traditional sockets
- Robust all-metal contact element
- Integrated edge-alignment frame with keying features
- Mechanical wipe at interface
- Built-in compression-stop within contact array
- Eutectic or Pb-free solder ball options

TECHNICAL INFORMATION:

Pitch	1.016 mm x 1.016 mm
Connector Size	50.0 mm x 50.0 mm
Contact Count	1366
Mated Thickness	1.7 mm*
Rec. Load/Contact	30 g
Contact Deflection	0.2 mm minimum
Insertions	> 20 mating cycles
Average Resistance	< 20 mΩ per position
Insulation Resistance	> 1 GΩ
Self Inductance	0.9 nH
Contact Wipe at Interface	Yes
Contact Plating	hard Au over Ni
Solder Ball	Eutectic
Solder Ball Diameter	0.6 mm
Operating Temperature	-40C to 85C
Storage Temperature	-50C to 100C



Low-Profile
1366-Position LGA Socket



PCBeam™ Connector Technology

* Nominal mated thickness after solder reflow.